

256K (32K x 8) CMOS EPROM

FEATURES

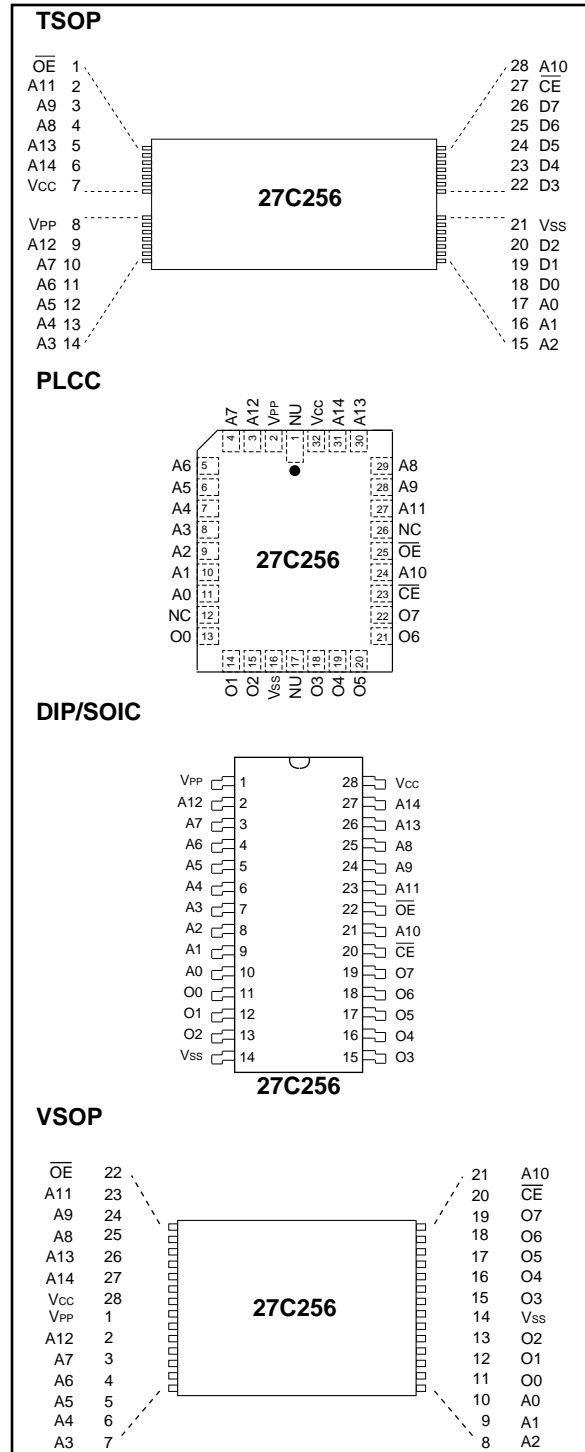
- High speed performance
 - 90 ns access time available
- CMOS Technology for low power consumption
 - 20 mA Active current
 - 100 μ A Standby current
- Factory programming available
- Auto-insertion-compatible plastic packages
- Auto ID aids automated programming
- Separate chip enable and output enable controls
- High speed "express" programming algorithm
- Organized 32K x 8: JEDEC standard pinouts
 - 28-pin Dual-in-line package
 - 32-pin PLCC Package
 - 28-pin SOIC package
 - 28-pin Thin Small Outline Package (TSOP)
 - 28-pin Very Small Outline Package (VSOP)
 - Tape and reel
- Data Retention > 200 years
- Available for the following temperature ranges:
 - Commercial: 0°C to +70°C
 - Industrial: -40°C to +85°C
 - Automotive: -40°C to +125°C

DESCRIPTION

The Microchip Technology Inc. 27C256 is a CMOS 256K bit electrically Programmable Read Only Memory (EPROM). The device is organized as 32K words by 8 bits (32K bytes). Accessing individual bytes from an address transition or from power-up (chip enable pin going low) is accomplished in less than 90 ns. This very high speed device allows the most sophisticated micro-processors to run at full speed without the need for WAIT states. CMOS design and processing enables this part to be used in systems where reduced power consumption and reliability are requirements.

A complete family of packages is offered to provide the most flexibility in applications. For surface mount applications, PLCC, SOIC, VSOP or TSOP packaging is available. Tape and reel packaging is also available for PLCC or SOIC packages.

PACKAGE TYPE



1.0 ELECTRICAL CHARACTERISTICS

1.1 Maximum Ratings*

VCC and input voltages w.r.t. VSS..... -0.6V to +7.25V
 VPP voltage w.r.t. VSS during programming -0.6V to +14.0V
 Voltage on A9 w.r.t. VSS -0.6V to +13.5V
 Output voltage w.r.t. VSS -0.6V to VCC +1.0V
 Storage temperature -65°C to +150°C
 Ambient temp. with power applied -65°C to +125°C

*Notice: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 1-1: PIN FUNCTION TABLE

| Name | Function |
|-----------------|---|
| A0-A14 | Address Inputs |
| \overline{CE} | Chip Enable |
| \overline{OE} | Output Enable |
| VPP | Programming Voltage |
| O0 - O7 | Data Output |
| VCC | +5V Power Supply |
| VSS | Ground |
| NC | No Connection; No Internal Connection |
| NU | Not Used; No External Connection Is Allowed |

TABLE 1-2: READ OPERATION DC CHARACTERISTICS

| VCC = +5V (±10%) Commercial: Tamb = 0°C to +70°C Industrial: Tamb = -40°C to +85°C Extended (Automotive): Tamb = -40°C to +125°C | | | | | | | |
|---|------------------|--------------------------------------|--------------------------------------|----------------------|---------------------------|----------------|--|
| Parameter | Part* | Status | Symbol | Min. | Max. | Units | Conditions |
| Input Voltages | all | Logic "1" Logic "0" | V _{IH} V _{IL} | 2.0 -0.5 | V _{CC} +1 0.8 | V V | |
| Input Leakage | all | — | I _{LI} | -10 | 10 | µA | V _{IN} = 0 to V _{CC} |
| Output Voltages | all | Logic "1" Logic "0" | V _{OH} V _{OL} | 2.4 | 0.45 | V V | I _{OH} = -400 µA I _{OL} = 2.1 mA |
| Output Leakage | all | — | I _{LO} | -10 | 10 | µA | V _{OUT} = 0V to V _{CC} |
| Input Capacitance | all | — | C _{IN} | — | 6 | pF | V _{IN} = 0V; Tamb = 25°C; f = 1 MHz |
| Output Capacitance | all | — | C _{OUT} | — | 12 | pF | V _{OUT} = 0V; Tamb = 25°C; f = 1 MHz |
| Power Supply Current, Active | C I, E | TTL input TTL input | I _{CC1} I _{CC2} | — | 20 25 | mA mA | V _{CC} = 5.5V; V _{PP} = V _{CC} f = 1 MHz; $\overline{OE} = \overline{CE} = V_{IL}$; I _{OUT} = 0 mA; V _{IL} = -0.1 to 0.8V; V _{IH} = 2.0 to V _{CC} ; Note 1 |
| Power Supply Current, Standby | C I, E all | TTL input TTL input CMOS input | I _{CC(S)} | — | 2 3 100 | mA mA µA | $\overline{CE} = V_{CC} \pm 0.2V$ |
| I _{PP} Read Current V _{PP} Read Voltage | all all | Read Mode Read Mode | I _{PP} V _{PP} | V _{CC} -0.7 | 100 V _{CC} | µA V | V _{PP} = 5.5V Note 2 |

* Parts: C=Commercial Temperature Range; I, E=Industrial and Extended Temperature Ranges

Note 1: Typical active current increases .75 mA per MHz up to operating frequency for all temperature ranges.

Note 2: V_{CC} must be applied before V_{PP}, and be removed simultaneously or after V_{PP}.

TABLE 1-3: READ OPERATION AC CHARACTERISTICS

| AC Testing Waveform: $V_{IH} = 2.4V$ and $V_{IL} = 0.45V$; $V_{OH} = 2.0V$ $V_{OL} = 0.8V$ Output Load: 1 TTL Load + 100 pF Input Rise and Fall Times: 10 ns Ambient Temperature: Commercial: $T_{amb} = 0^{\circ}C$ to $+70^{\circ}C$ Industrial: $T_{amb} = -40^{\circ}C$ to $+85^{\circ}C$ Automotive: $T_{amb} = -40^{\circ}C$ to $+125^{\circ}C$ | | | | | | | | | | | | | |
|---|------|------------|-----|------------|-----|-----------|-----|-----------|-----|-----------|-----|-------|--|
| Parameter | Sym | 27C256-90* | | 27C256-10* | | 27C256-12 | | 27C256-15 | | 27C256-20 | | Units | Conditions |
| | | Min | Max | Min | Max | Min | Max | Min | Max | Min | Max | | |
| Address to Output Delay | tACC | — | 90 | — | 100 | — | 120 | — | 150 | — | 200 | ns | $\overline{CE} = \overline{OE} = V_{IL}$ |
| \overline{CE} to Output Delay | tCE | — | 90 | — | 100 | — | 120 | — | 150 | — | 200 | ns | $\overline{OE} = V_{IL}$ |
| \overline{OE} to Output Delay | tOE | — | 40 | — | 45 | — | 55 | — | 65 | — | 75 | ns | $\overline{CE} = V_{IL}$ |
| \overline{CE} or \overline{OE} to O/P High Impedance | tOFF | 0 | 30 | 0 | 30 | 0 | 35 | 0 | 50 | 0 | 55 | ns | |
| Output Hold from Address \overline{CE} or \overline{OE} , whichever goes first | tOH | 0 | — | 0 | — | 0 | — | 0 | — | 0 | — | ns | |

* -10, -90 AC Testing Waveform: $V_{IH} = 2.4V$ and $V_{IL} = .45V$; $V_{OH} = 1.5V$ and $V_{OL} = 1.5V$
Output Load: 1 TTL Load + 30pF

FIGURE 1-1: READ WAVEFORMS

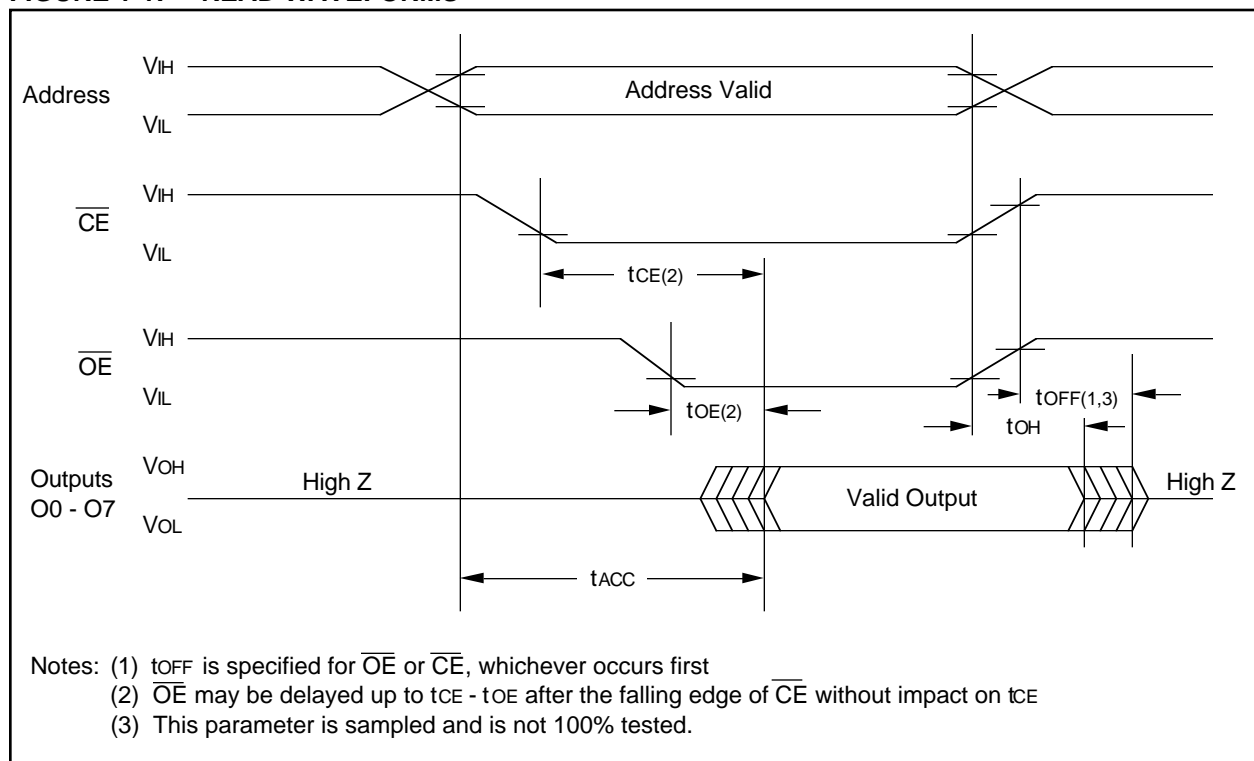


TABLE 1-4: PROGRAMMING DC CHARACTERISTICS

| Ambient Temperature: $T_{amb} = 25^{\circ}\text{C} \pm 5^{\circ}\text{C}$ $V_{CC} = 6.5\text{V} \pm 0.25\text{V}$, $V_{PP} = V_H = 13.0\text{V} \pm 0.25\text{V}$ | | | | | | |
|---|----------|-----------|------|------------|---------------|---------------------------------|
| Parameter | Status | Symbol | Min | Max. | Units | Conditions |
| Input Voltages | Logic"1" | V_{IH} | 2.0 | $V_{CC}+1$ | V | |
| | Logic"0" | V_{IL} | -0.1 | 0.8 | V | |
| Input Leakage | — | I_{LI} | -10 | 10 | μA | $V_{IN} = 0\text{V to } V_{CC}$ |
| Output Voltages | Logic"1" | V_{OH} | 2.4 | | V | $I_{OH} = -400\ \mu\text{A}$ |
| | Logic"0" | V_{OL} | | 0.45 | V | $I_{OL} = 2.1\ \text{mA}$ |
| VCC Current, program & verify | — | I_{CC2} | — | 20 | mA | Note 1 |
| VPP Current, program | — | I_{PP2} | — | 25 | mA | Note 1 |
| A9 Product Identification | — | V_H | 11.5 | 12.5 | V | |

Note 1: VCC must be applied simultaneously or before VPP and removed simultaneously or after VPP

TABLE 1-5: PROGRAMMING AC CHARACTERISTICS

| for Program, Program Verify and Program Inhibit Modes | | | | | | |
|--|--------|------|------|---------------|---------------------------|--|
| AC Testing Waveform: $V_{IH}=2.4\text{V}$ and $V_{IL}=0.45\text{V}$; $V_{OH}=2.0\text{V}$; $V_{OL}=0.8\text{V}$ Output Load: 1 TTL Load + 100pF Ambient Temperature: $T_{amb}=25^{\circ}\text{C} \pm 5^{\circ}\text{C}$ $V_{CC}= 6.5\text{V} \pm 0.25\text{V}$, $V_{PP} = V_H = 13.0\text{V} \pm 0.25\text{V}$ | | | | | | |
| Parameter | Symbol | Min. | Max. | Units | Remarks | |
| Address Set-Up Time | tAS | 2 | — | μs | | |
| Data Set-Up Time | tDS | 2 | — | μs | | |
| Data Hold Time | tDH | 2 | — | μs | | |
| Address Hold Time | tAH | 0 | — | μs | | |
| Float Delay (2) | tDF | 0 | 130 | ns | | |
| VCC Set-Up Time | tVCS | 2 | — | μs | | |
| Program Pulse Width (1) | tPW | 95 | 105 | μs | 100 μs typical | |
| $\overline{\text{CE}}$ Set-Up Time | tCES | 2 | — | μs | | |
| $\overline{\text{OE}}$ Set-Up Time | tOES | 2 | — | μs | | |
| VPP Set-Up Time | tVPS | 2 | — | μs | | |
| Data Valid from $\overline{\text{OE}}$ | tOE | — | 100 | ns | | |

Note 1: For express algorithm, initial programming width tolerance is $100\ \mu\text{s} \pm 5\%$.

Note 2: This parameter is only sampled and not 100% tested. Output float is defined as the point where data is no longer driven (see timing diagram).

FIGURE 1-2: PROGRAMMING WAVEFORMS

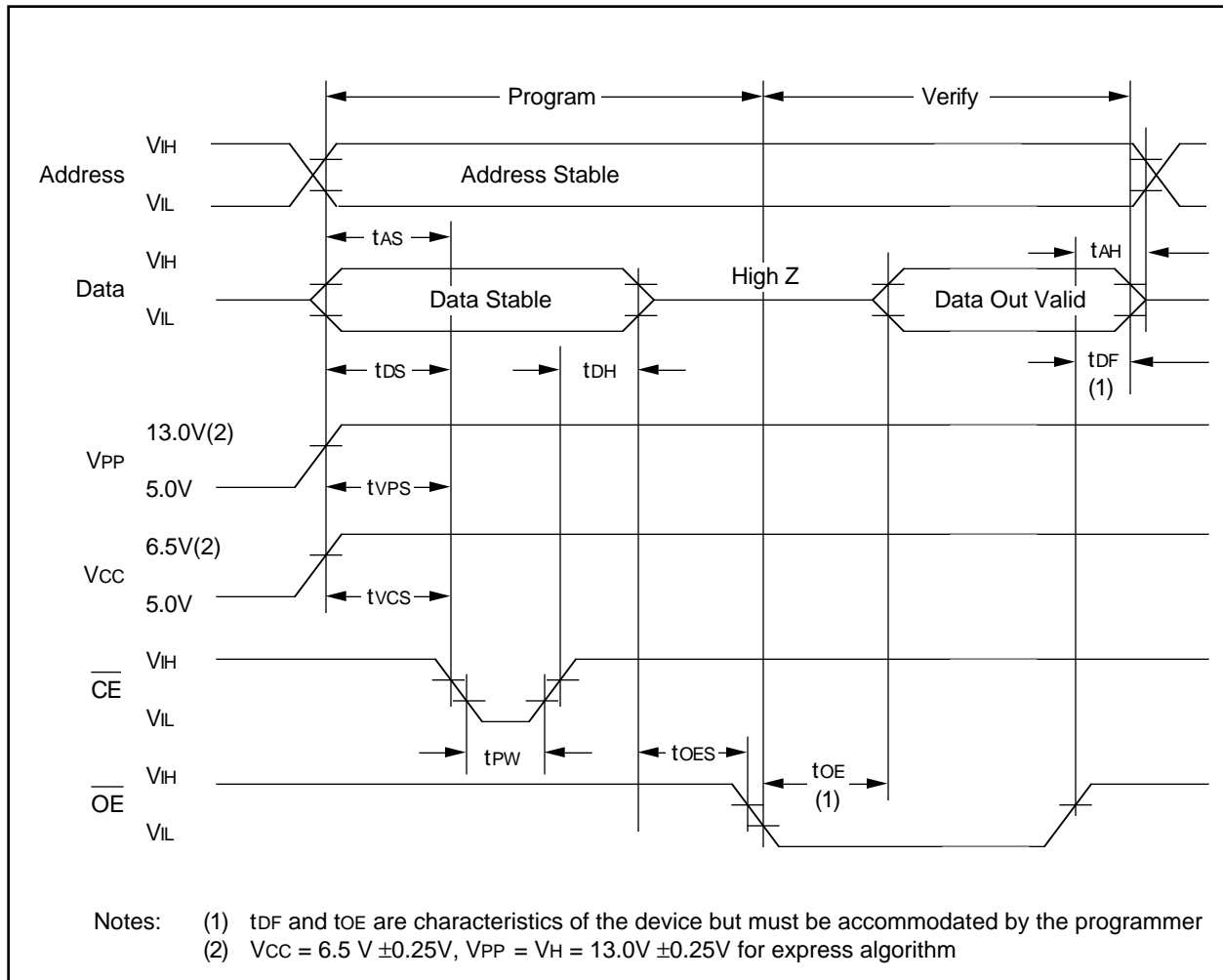


TABLE 1-6: MODES

| Operation Mode | \overline{CE} | OE | VPP | A9 | O0 - O7 |
|-----------------|-----------------|-----|-----|----|---------------|
| Read | VIL | VIL | VCC | X | DOUT |
| Program | VIL | VIH | VH | X | DIN |
| Program Verify | VIH | VIL | VH | X | DOUT |
| Program Inhibit | VIH | VIH | VH | X | High Z |
| Standby | VIH | X | VCC | X | High Z |
| Output Disable | VIL | VIH | VCC | X | High Z |
| Identity | VIL | VIL | VCC | VH | Identity Code |

X = Don't Care

1.2 Read Mode

(See Timing Diagrams and AC Characteristics)

Read Mode is accessed when:

- the \overline{CE} pin is low to power up (enable) the chip
- the \overline{OE} pin is low to gate the data to the output pins

For Read operations, if the addresses are stable, the address access time (t_{ACC}) is equal to the delay from \overline{CE} to output (t_{CE}). Data is transferred to the output after a delay from the falling edge of \overline{OE} (t_{OE}).

1.3 Standby Mode

The standby mode is defined when the \overline{CE} pin is high (VIH) and a program mode is not defined.

When these conditions are met, the supply current will drop from 20 mA to 100 μ A.

1.4 Output Enable

This feature eliminates bus contention in multiple bus microprocessor systems and the outputs go to a high impedance when the following condition is true:

- The \overline{OE} pin is high and the program mode is not defined.

1.5 Erase Mode (U.V. Windowed Versions)

Windowed products offer the ability to erase the memory array. The memory matrix is erased to the all 1's state when exposed to ultraviolet light. To ensure complete erasure, a dose of 15 watt-second/cm² is required. This means that the device window must be placed within one inch and directly underneath an ultraviolet lamp with a wavelength of 2537 Angstroms, intensity of 12,000 μ W/cm² for approximately 20 minutes.

1.6 Programming Mode

The Express Algorithm has been developed to improve on the programming throughput times in a production environment. Up to ten 100-microsecond pulses are applied until the byte is verified. No overprogramming is required. A flowchart of the express algorithm is shown in Figure 1-3.

Programming takes place when:

- VCC is brought to the proper voltage,
- VPP is brought to the proper VH level,
- the \overline{OE} pin is high, and
- the \overline{CE} pin is low.

Since the erased state is "1" in the array, programming of "0" is required. The address to be programmed is set via pins A0-A14 and the data to be programmed is presented to pins O0-O7. When data and address are stable, a low going pulse on the \overline{CE} line programs that location.

1.7 Verify

After the array has been programmed it must be verified to ensure all the bits have been correctly programmed. This mode is entered when all the following conditions are met:

- VCC is at the proper level,
- VPP is at the proper VH level,
- the \overline{CE} line is high, and
- the \overline{OE} line is low.

1.8 Inhibit

When programming multiple devices in parallel with different data, only \overline{CE} need be under separate control to each device. By pulsing the \overline{CE} line low on a particular device, that device will be programmed; all other devices with \overline{CE} held high will not be programmed with the data, although address and data will be available on their input pins.

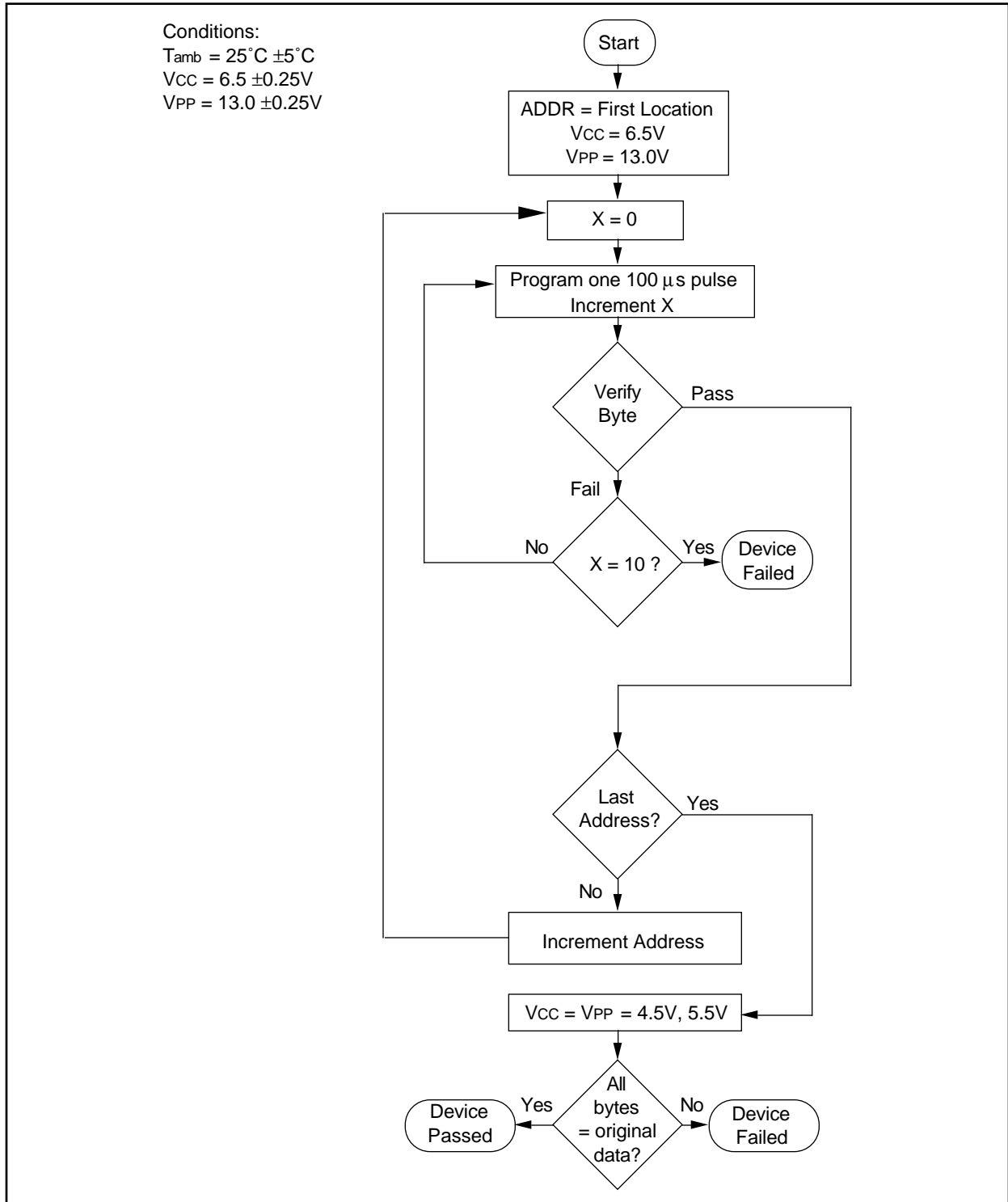
1.9 Identity Mode

In this mode specific data is output which identifies the manufacturer as Microchip Technology Inc. and device type. This mode is entered when Pin A9 is taken to VH (11.5V to 12.5V). The \overline{CE} and \overline{OE} lines must be at VIL. A0 is used to access any of the two non-erasable bytes whose data appears on O0 through O7.

| Pin \rightarrow | Input | Output | | | | | | | | |
|--------------------------|-------|--------|--------|--------|--------|--------|--------|--------|--------|-------------|
| Identity \downarrow | A0 | 0 7 | 0 6 | 0 5 | 0 4 | 0 3 | 0 2 | 0 1 | 0 0 | H e x |
| Manufacturer | VIL | 0 | 0 | 1 | 0 | 1 | 0 | 0 | 1 | 29 |
| Device Type* | VIH | 1 | 0 | 0 | 0 | 1 | 1 | 0 | 0 | 8C |

* Code subject to change

FIGURE 1-3: PROGRAMMING EXPRESS ALGORITHM



27C256

27C256 Product Identification System

To order or to obtain information (e.g., on pricing or delivery), please use listed part numbers, and refer to factory or listed sales offices.

| 27C256 - 90 I /TS | | | |
|--------------------|--------|--|--|
| Package: | L | Plastic Leaded Chip Carrier | |
| | P | Plastic DIP | |
| | SO | Plastic SOIC | |
| | TS | Thin Small Outline Package (TSOP) 8x20mm | |
| | VS | Very Small Outline Package (VSOP) 8x13.4mm | |
| Temperature Range: | - | 0°C to +70°C | |
| | I | -40°C to +85°C | |
| | E | -40°C to +125°C | |
| Access Time: | 90 | 90 ns | |
| | 10 | 100 ns | |
| | 12 | 120 ns | |
| | 15 | 150 ns | |
| | 20 | 200 ns | |
| Device | 27C256 | 256K (32K x 8) CMOS EPROM | |

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